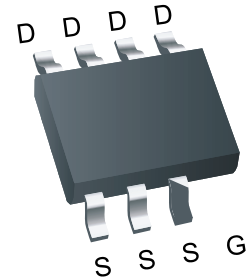


## P-Channel Enhancement Mode MOSFET

### Feature

- -100V/-4A  
 $R_{DS(ON)} = 74\text{ m}\Omega(\text{typ.}) @V_{GS} = -10V$   
 $R_{DS(ON)} = 82\text{ m}\Omega(\text{typ.}) @V_{GS} = -4.5V$
- 100% Avalanche Tested
- Reliable and Rugged
- Halogen Free and Green Devices Available  
 (RoHS Compliant)

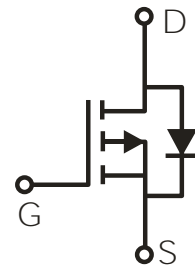
### Pin Description



SOP8L

### Applications

- Power Management in DC/DC converter
- Load switching



Single P-Channel MOSFET

### Ordering and Marking Information

 <b>S</b> <b>HYG850P10</b> XYMXXXXXX	Package Code S:SOP8L  Date Code XYMXXXXXX
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Note: HUAYI halogen free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI halogen free products meet or exceed the halogen free requirements of IPC/JEDEC J-STD-020 for MSL classification at halogen free peak reflow temperature. HUAYI defines “Green” to mean halogen free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
<b>Common Ratings</b> (Tc=25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage	-100	V	
V <sub>GSS</sub>	Gate-Source Voltage	±20	V	
T <sub>J</sub>	Junction Temperature Range	-55 to 175	°C	
T <sub>STG</sub>	Storage Temperature Range		°C	
I <sub>S</sub>	Source Current-Continuous(Body Diode)	Tc=25°C	-4	A
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulsed Drain Current *	Tc=25°C	-14	A
I <sub>D</sub>	Continuous Drain Current	Tc=25°C	-4	A
		Tc=100°C	-3	A
P <sub>D</sub>	Maximum Power Dissipation	Tc=25°C	3	W
		Tc=100°C	1.5	W
R <sub>JA</sub>	Thermal Resistance, Junction-to-Ambient **		50	°C/W
E <sub>AS</sub>	Single Pulsed-Avalanche Energy ***	L=0.3mH	60	mJ

Note: \* Repetitive rating; pulse width limited by max.junction temperature.

\*\* Surface mounted on 1in2 FR-4 board.

\*\*\* Limited by T<sub>Jmax</sub> , starting T<sub>J</sub>=25°C, L = 0.3mH, R<sub>G</sub>= 25 , V<sub>GS</sub> =-10V.

## Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG850P10LR1	Unit
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**Electrical Characteristics (Cont.)** (T<sub>c</sub> =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG850P10LR1			Unit
			Min	Typ.	Max	
<b>Dynamic Characteristics</b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	-	8.4	-	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-25V, Frequency= 1MHz	-	2652	-	pF
C <sub>oss</sub>	Output Capacitance					
C <sub>rss</sub>	Reverse Transfer Capacitance					
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-50V, R <sub>G</sub> =2.5Ω, I <sub>DS</sub> =-3A, V <sub>GS</sub> =-10V	-	9.4	-	ns
T <sub>r</sub>	Turn-on Rise Time					
t <sub>d(OFF)</sub>	Turn-off Delay Time					
T <sub>f</sub>	Turn-off Fall Time					

## Typical Operating Characteristics

Figure 1: Power Dissipation

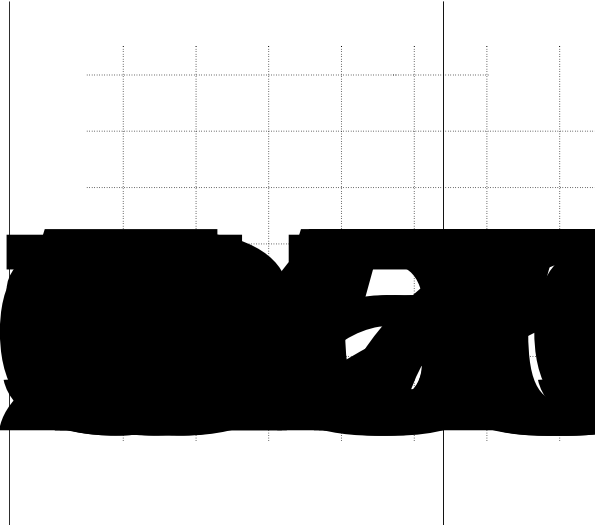


Figure 2: Drain Current

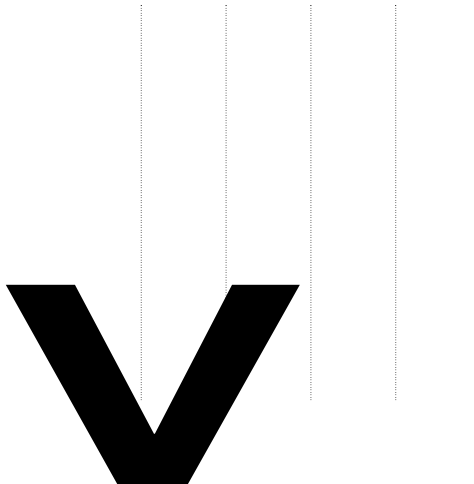
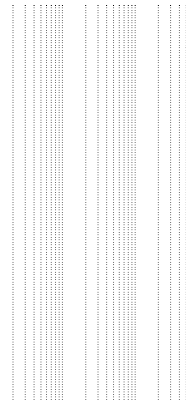
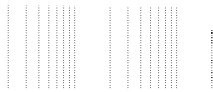


Figure 3: Safe Operation Area

Figure 4: Thermal Transient Impedance

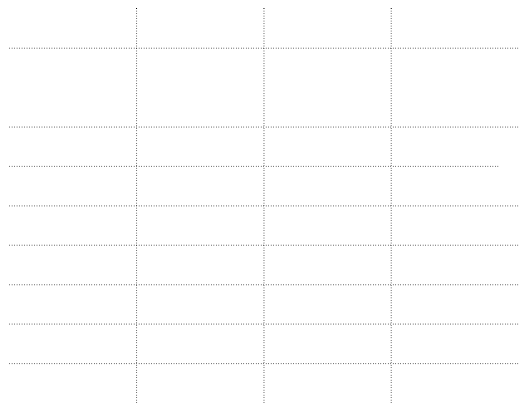
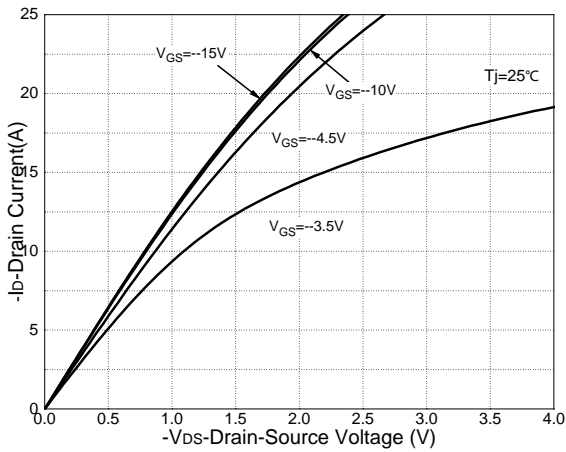
\*Notes:



2.  $T_c = 25^\circ\text{C}$  is Area

Figure 5: Output Characteristics

Figure 6: Drain-Source On Resistance



## Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

Figure 8: Source-Drain Diode Forward



Figure 9: Capacitance Characteristics

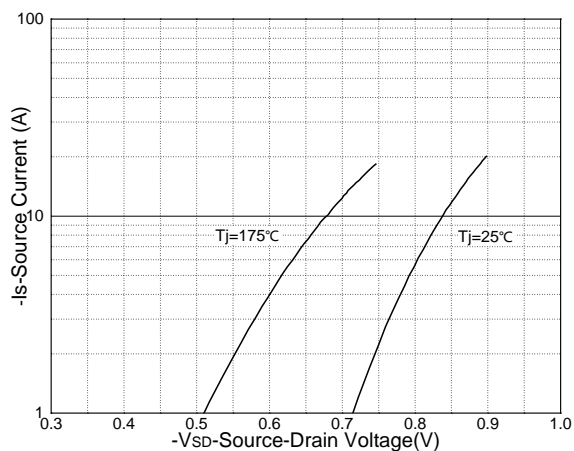
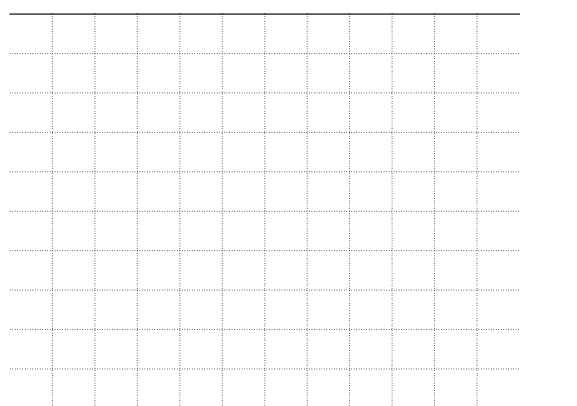
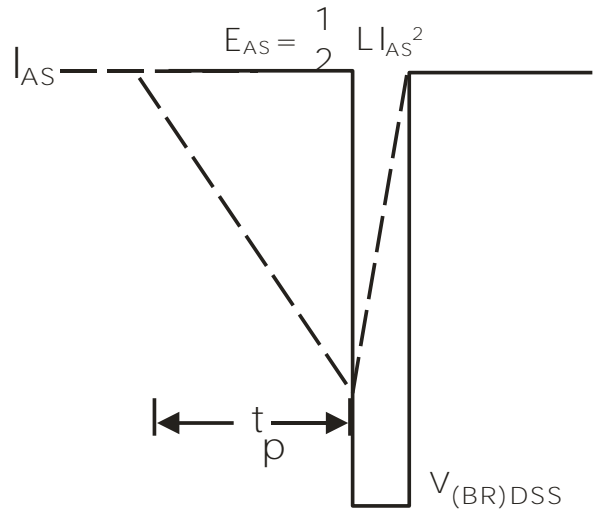
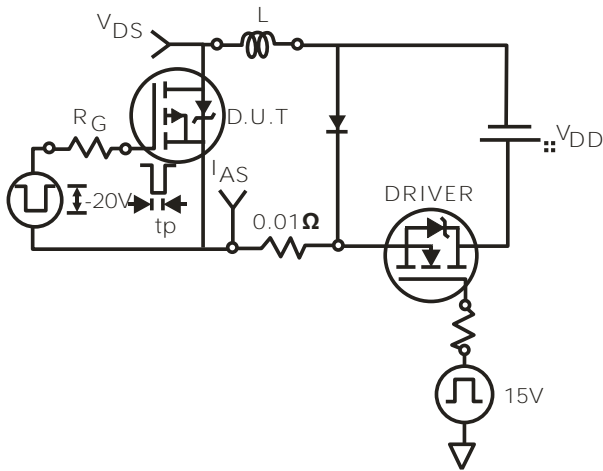


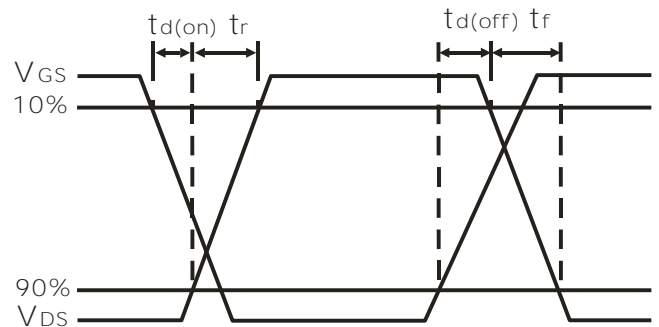
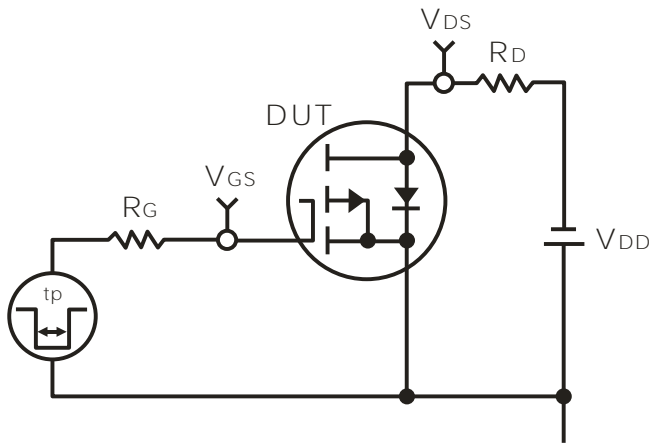
Figure 10: Gate Charge Characteristics



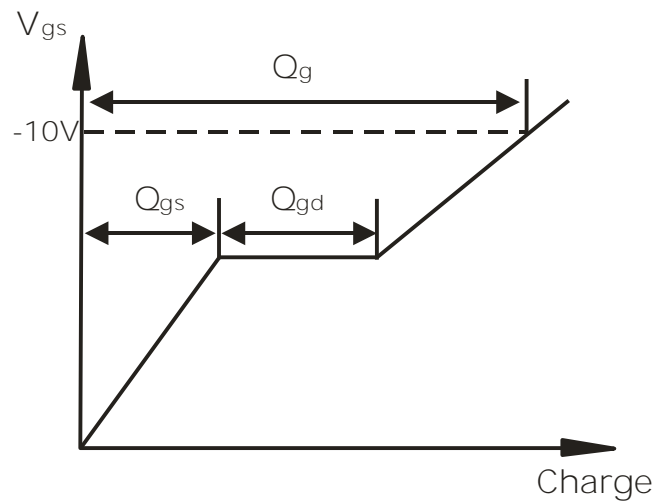
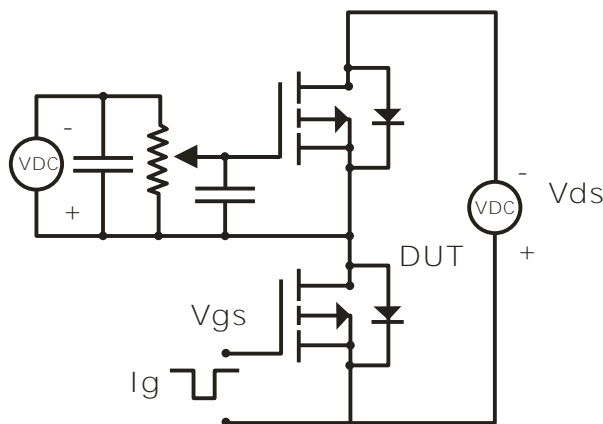
**Avalanche Test Circuit**



**Switching Time Test Circuit**



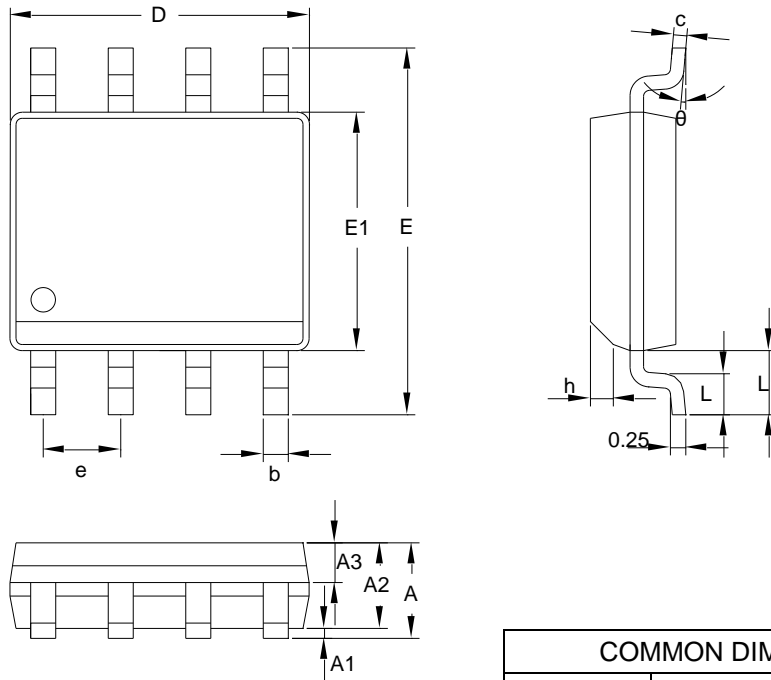
**Gate Charge Test Circuit**



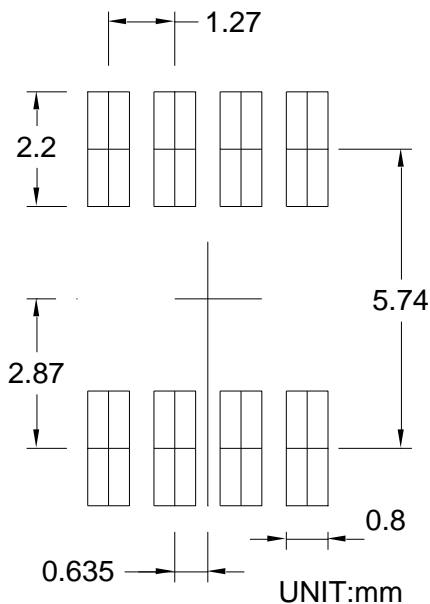
## Device Per Unit

Package Type	Unit	Quantity
SOP8L	Reel	2500

## Package Information



### RECOMMENDED LAND PATTERN

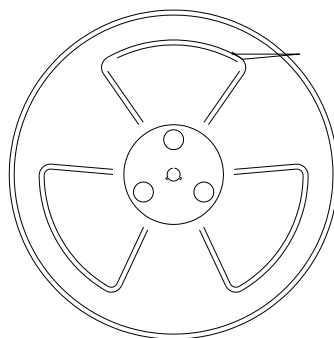
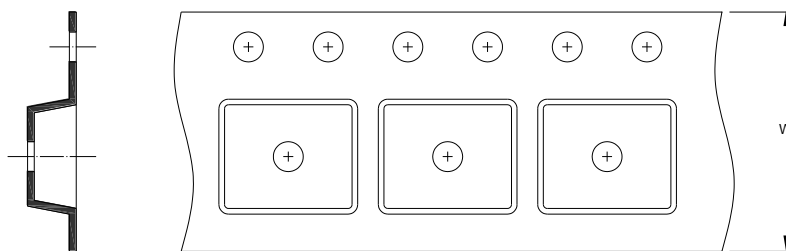


COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	-	-	1.75
A1	0.10	-	0.225
A2	1.30	1.40	1.50
A3	0.60	0.65	0.70
b	0.39	-	0.47
c	0.20	-	0.24
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27 BSC		
h	0.25	-	0.50
L	0.50	-	0.80
L1	1.05 REF		
θ	0°	-	8°

Note:

1. Follow JEDEC MS-012AA.
2. Dimension D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

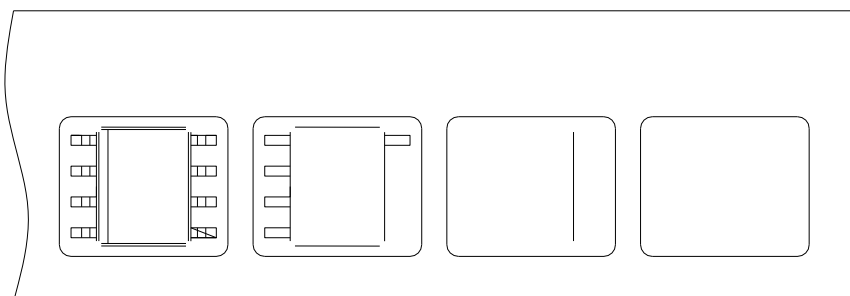
## Carrier Tape & Reel Dimensions



Application	A	H	T1	C	d	D	W	E1	F
SOP8L	330 2.00	50 MIN	12.4+2.00 -0.20	13.0+0.50 -0.20	1.5 MIN	20.2 MIN	12.0 0.30	1.75 0.10	5.5 0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 0.10	8.0 0.10	2.0 0.05	1.5+0.10 -0.00	1.5 MIN	0.6+0.00 -0.40	6.40 0.20	5.20 0.20	2.10 0.20

## Taping Direction Information

USER DIRECTION OF FEED





**Classification Profile**



**Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_P$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_P$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_P$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_P$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature ( $t_P$ ) is defined as a supplier minimum and a user maximum.		

Table 1.SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2.Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> ≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168 /500 Hrs, V <sub>gs</sub> 100% @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	250/500 Cycles, -55°C~150°C

## Customer Service

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